



**RJ9F ADHESIVE/SEALANT
FORMULATION 5370**

RJ9F 5370 is a B-staged adhesive/sealant for sealing electronic packages. It is a system for use on ceramic, plastic, glass and metal covers. The reactivity and flow characteristics are tailored for clip and bake or automated cycles

TYPICAL PROPERTIES

Max operating temperature (continuous), °C	NA
Outgassing	NA
Moisture absorption (24 hr. soak in water @ 100°C)	<2.0%
Total ionic content (specific electrical conductance), mS/m	NA
Extractable Ions, ppm	< 10
Hydrolysable chloride content, ppm (MIL-STD 883H Method 5011.5)	NA
Tg by DSC, °C	100
Modulus, psi	NA
CTE, ppm/°C	30
Dielectric constant (@ 1MHz)	NA
Volume resistivity, Ohm-cm	NA
Thermal conductivity, W/m-k	NA

TYPICAL SEALED PACKAGE PERFORMANCE PROPERTIES*

Reflow temperature, °C	NA
Lap shear strength (gold/ceramic @ 25°C), psi	NA

**These values may vary depending upon the materials to which the epoxy is adhered. All above data is based on sealed packages consisting of a ceramic header and a ceramic lid.*

SEALING AND CURING

Typical curing cycles are 30 minutes at 150°C, 2 hours at 120°C, or 3 hours 110°C under 1-5 psi of pressure. For alternate curing practices or automatic sealing procedures, please consult RJR Technologies, INC. Customer Service. (Phone 510-638-5901 or Fax 510-638-5958)

STORAGE AND HANDLING

Keep parts with the material in vacuum sealed bag with dry-packs at 3-8°C and <50% RH. Shelf life of the material when stored under refrigerated conditions (3-8°C) is 6 months from the date of manufacture. Room temperature and frozen storage conditions may be appropriate for some applications. Please consult RJR Technologies Customer Service for specific storage options.

REGULATORY

This product is RoHS compliant.

NOTICE

This data is provided for guideline purposes. No warranty is made on the actual use. Customers should perform their own tests and qualifications.